

ABSTRACT

A semiconductor module includes a module substrate having a first side extending in a first direction, a plurality of upper packages disposed on a top surface of the module substrate and arranged in rows extending in the first direction, and a passive element
5 disposed on the top surface of the module substrate. At least a portion of the passive element overlaps one of the upper packages when viewed in a plan view, and the upper packages of a first row are arranged to be shifted with respect to the upper packages of a second row in the first direction.

FIG. 1A